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B23K 20/00(21)Application number : **2002-371962**(71)Applicant : **HITACHI METALS LTD**(22)Date of filing : **24.12.2002**(72)Inventor : **UEMURA NORIO**
TANIGUCHI SHIGERU**(54) TARGET**

(57)Abstract:

PROBLEM TO BE SOLVED: To provide an inexpensive target capable of reducing particles produced during the sputtering that is a problem in a multi-fraction target applied to cope with the jumboizing of the target for thin film deposition used in manufacturing products of flat panel displays such as semi-conductor, magnetic disk and liquid crystal at low cost.

SOLUTION: In the target, end faces thereof are bonded to each other through solid phase diffusion. Friction press-bonding and friction stir-bonding are applicable for a method of solid phase diffusion bonding when a hot isostatic press is used.

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